

### **Features**

• 30V/30A,

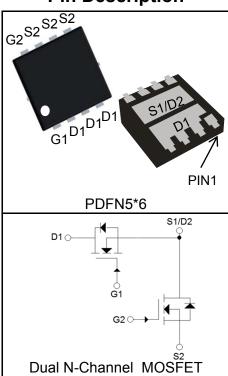
 $R_{DS (ON)} = 7m\Omega(Typ.)@V_{GS} = 10V$  $R_{DS (ON)} = 9.5m\Omega(Typ.)@V_{GS} = 4.5V$ 

- Fast Switching Speed
- Low gate Charge
- 100% avalanche tested
- Lead Free and Green Devices Available (RoHS Compliant)

## **Applications**

- · Switching Application Systems
- DC/DC Converters

## **Pin Description**



## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit					
Common Ra	tings (T <sub>C</sub> =25°C Unless Otherwise Noted)		-					
V <sub>DSS</sub>	Drain-Source Voltage	30	V					
V <sub>GSS</sub>	Gate-Source Voltage	±20	V					
T <sub>J</sub>	Maximum Junction Temperature	150	°C					
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C					
I <sub>S</sub>	Diode Continuous Forward Current	20	Α					
Mounted on Large Heat Sink								
I <sub>DP</sub> (1)	300μs Pulse Drain Current Tested	T <sub>C</sub> =25°C	120	Α				
I <sub>D</sub> <sup>©</sup>	Continuous Proin Current®T (V =4.5V)	30						
	Continuous Drain Current@T <sub>C</sub> (V <sub>GS</sub> =4.5V)	T <sub>C</sub> =100°C	19	Α				
		T <sub>A</sub> =25°C	10					
	Continuous Drain Current@T <sub>A</sub> (V <sub>GS</sub> =4.5V) <sup>3</sup>	T <sub>A</sub> =70°C	8					
$P_{D}$	Maximum Power Dissipation@T <sub>C</sub>	T <sub>C</sub> =25°C	29					
	INIAAIITIUITI FOWEI DISSIPALIOII@10	12	W					
	5 5 5 3	T <sub>A</sub> =25°C	3.1	VV				
	Maximum Power Dissipation@T <sub>A</sub>	2						



Symbol	Parameter	Rating	Unit						
$R_{\theta JC}$	Thermal Resistance-Junction to Case	4.2	°C/W						
$R_{ heta JA}^{\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ $	Thermal Resistance-Junction to Ambient	40	°C/W						
Drain-Source Avalanche Ratings									
E <sub>AS</sub>	Avalanche Energy, Single Pulsed	49	mJ						

## **Electrical Characteristics** (T<sub>C</sub>=25°C Unless Otherwise Noted)

Comple at	Dorom eter	Tagt 0-	F	11			
Symbol	Parameter	Test Co	Min.	Тур.	Max.	Unit	
Static Cha	racteristics			•			
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0V, $I_{DS}$ =2	50µA	30			V
	Zara Cata Valtaga Drain Current	$V_{DS}$ =30V, $V_{GS}$ =	=0V			1	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current				30	μΑ	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{DS} = 2$	250µA	1.2		2.5	V
I <sub>GSS</sub>	Gate Leakage Current	$V_{GS}$ =±20V, $V_{DS}$	<sub>S</sub> =0V			±100	nA
5	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =		7	9	mΩ	
R <sub>DS(ON)</sub>	Diain-Source On-State Resistance	$V_{GS}$ =4.5V, $I_{DS}$ =		9.5	12	mΩ	
Diode Cha	racteristics						
V <sub>SD</sub> <sup>(5)</sup>	Diode Forward Voltage	I <sub>SD</sub> =20A, V <sub>GS</sub> =			1.2	V	
<b>t</b> rr	Reverse Recovery Time	l00		15		ns	
Qrr	Reverse Recovery Charge	Isb=20A, dlsb/c	it=100A/μS		8		nC
Dynamic C	Characteristics <sup>©</sup>						
R <sub>G</sub>	Gate Resistance	$V_{GS}$ =0 $V$ , $V_{DS}$ =0	V,F=1MHz		1		Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V,			670		pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =15V, Frequency=1.0	)MH <del>z</del>		180		
C <sub>rss</sub>	Reverse Transfer Capacitance	rrequeriey r.c		75			
t <sub>d(ON)</sub>	Turn-on Delay Time				5		
t <sub>r</sub>	Turn-on Rise Time	V <sub>DD</sub> =15V, R <sub>L</sub> =0 I <sub>DS</sub> =20A, V <sub>GEN</sub> =			10		ne
t <sub>d(OFF)</sub>	Turn-off Delay Time	$R_G=3\Omega$		15		ns	
t <sub>f</sub>	Turn-off Fall Time			4			
Gate Char	ge Characteristics <sup>®</sup>						
$Q_g$	Total Gate Charge	V 00111		12			
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =24V, V <sub>GS</sub> = I <sub>DS</sub> =20A		3		nC	
$Q_{gd}$	Gate-Drain Charge			4			



Notes:

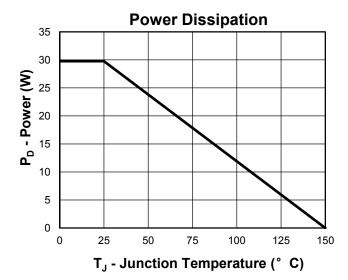
- ①Pulse width limited by safe operating area.
- ②Calculated continuous current based on maximum allowable junction temperature.
- ③When mounted on 1 inch square copper board, t≤10sec.
- 4Limited by T<sub>Jmax</sub>, I<sub>AS</sub> =14A, V<sub>DD</sub> = 24V, R<sub>G</sub> = 50Ω, Starting T<sub>J</sub> = 25°C.
- ⑤Pulse test;Pulse width≤300μs, duty cycle≤2%.
- **©**Guaranteed by design, not subject to production testing.

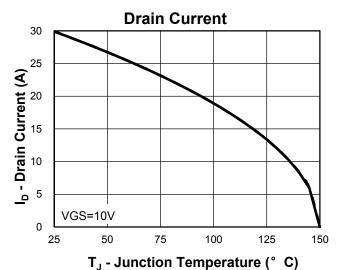
### **Ordering and Marking Information**

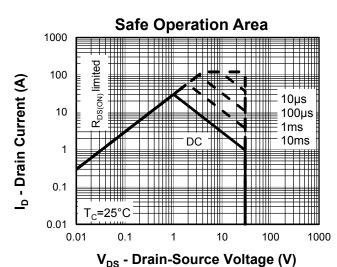
Device	Marking	Package	Packaging	Quantity	Reel Size	Tape width	
RU30J30M	RU30J30M	PDFN5060	Tape&Reel	3000	13"	12mm	

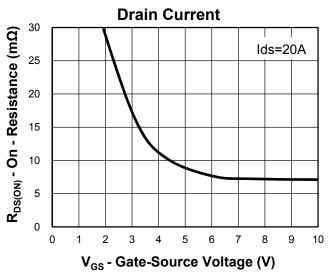


## **Typical Characteristics**

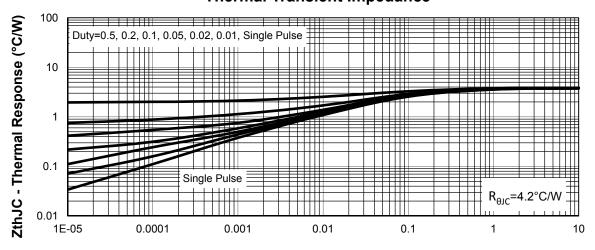








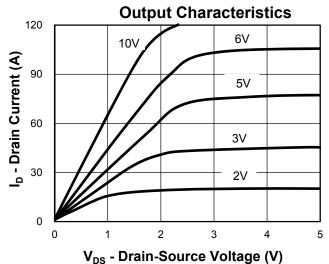
### **Thermal Transient Impedance**

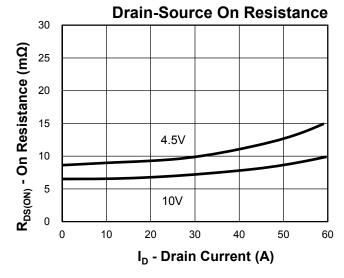


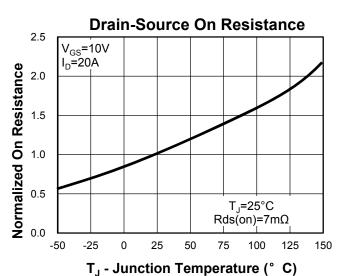
**Square Wave Pulse Duration (sec)** 

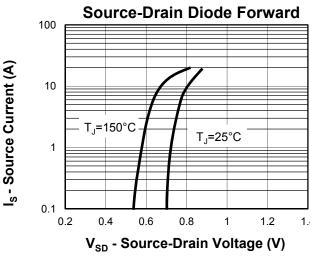


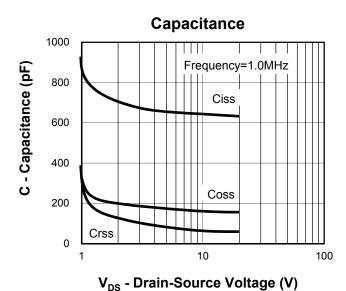
## **Typical Characteristics**

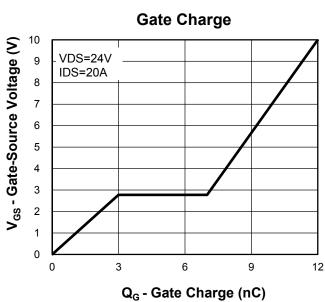






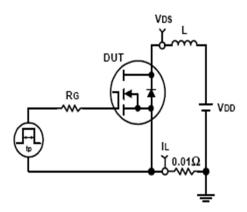


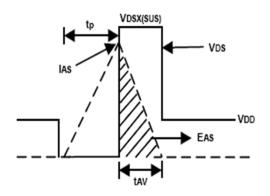




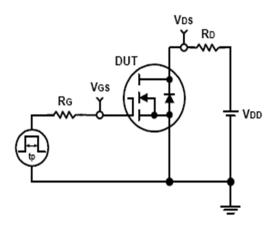


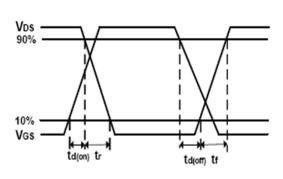
## **Avalanche Test Circuit and Waveforms**





## **Switching Time Test Circuit and Waveforms**



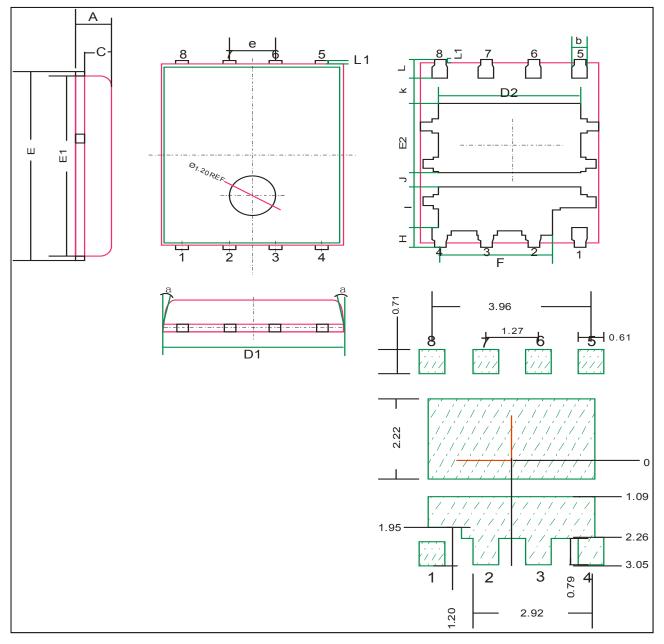


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# **Package Information**

# PDFN5060



SYMBOL	MM			INCH			SYMBOL	MM			INCH		
SIMDOL	MIN	NOM	MAX	MIN	NOM	MAX	IAX STMDOL	MIN	NOM	MAX	MIN	NOM	MAX
A	0.90	1.00	1.10	0.035	0.039	0.043	E1	5.70	5. 75	5.80	0.224	0. 226	0. 228
b	0.33	0.41	0.51	0.013	0.016	0.020	E2	2.02	2.17	2. 32	0.079	0.085	0.091
С	0.20	0.25	0.30	0.008	0.010	0.012	е	1. 27BSC			0. 05BSC		
D1	4.80	4.90	5.00	0.189	0. 193	0.197	Н	0.48	0.58	0.68	0.018	0.022	0.026
D2	3.61	3.81	3.96	0.142	0.150	0.156	L	0.51	0.61	0.71	0.020	0.024	0.028
L1	0.06	0.13	0.20	0.002	0.005	0.008							
Е	5. 90	6.00	6.10	0. 232	0. 236	0.240	@	0°	*	12°	*	10°	12°
K	0.50	*	*	0.019	*	*	J	0.40	0.50	0.60	0.015	0.019	0.023
I	1. 22	1.32	1.42	0.048	0.051	0.055	F	2.87	3. 07	3. 22	0.112	0. 12	0.126



### **Customer Service**

### Worldwide Sales and Service:

Sales@ruichips.com

### **Technical Support:**

Technical@ruichips.com

### **Investor Relations Contacts:**

Investor@ruichips.com

### **Marcom Contact:**

Marcom@ruichips.com

### **Editorial Contact:**

Editorial@ruichips.comm

#### **HR Contact:**

HR@ruichips.com

### **Legal Contact:**

Legal@ruichips.com

### Shen Zhen RUICHIPS Semiconductor CO., LTD

4th Floor, Block 8, Changyuan New Material Port, Keyuan Middle Road, Science & Industry Park, Nanshan District, Shenzhen, CHINA

**TEL:** (86-755) 8311-5334 **FAX:** (86-755) 8311-4278

E-mail: Sales-SZ@ruichips.com